

Title (en)
BALUN CIRCUITS

Publication
EP 0213864 A3 19880907 (EN)

Application
EP 86306357 A 19860818

Priority
GB 8521727 A 19850831

Abstract (en)
[origin: EP0213864A2] A Balun circuit for an integrated circuit having a small area and constructed using known semi-conductor fabrication processes. The balun circuit comprises two metallic strips (3,5) on a dielectric substrate (1) the strips (3,5) being substantially parallel to one another with a gap (7) there between and the second strip (5) having a length (21) to be equal to a quarter wavelength of the input signal, the values of the gap and strip widths (13,19) being predetermined such that the output impedances of the first and second metallic strips (3,5) respectively are substantially equal.

IPC 1-7
H01P 5/10

IPC 8 full level
H01P 5/10 (2006.01)

CPC (source: EP)
H01P 5/10 (2013.01)

Citation (search report)

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- [X] EP 0146086 A2 19850626 - POLSKA AKAD NAUK CENTRUM [PL]
- [Y] US 3848198 A 19741112 - DE BRECHT R, et al
- [A] US 3721912 A 19730320 - ROSS G
- [X] 14TH EUROPEAN MICROWAVE CONFERENCE, Liège, 10th - 13th September 1984, pages 166-171, Microwave Exhibitions and Publishers Ltd, Tunbridge Wells, Kent, GB; W. MARCZEWSKI et al.: "The overlapped microstrip for MICs and MMICs"

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Designated contracting state (EPC)
AT BE CH DE FR IT LI LU NL SE

DOCDB simple family (publication)
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